



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

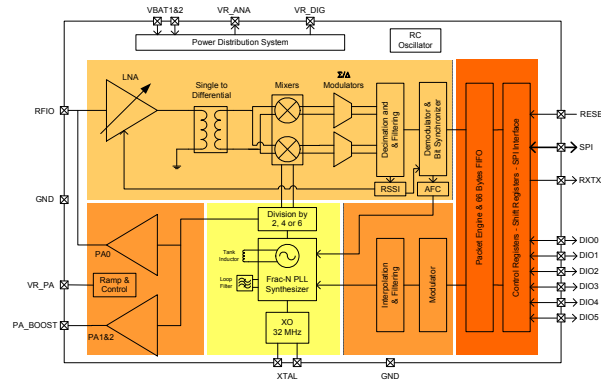
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SX1231H Transceiver

Low Power Integrated UHF Transceiver with On-Chip +20dBm PA



GENERAL DESCRIPTION

The SX1231H is a highly integrated RF transceiver capable of operation over a wide frequency range, including the 433, 868 and 915 MHz license-free ISM (Industry Scientific and Medical) frequency bands. Its highly integrated architecture allows for a minimum of external components whilst maintaining maximum design flexibility. All major RF communication parameters are programmable and most of them can be dynamically set. The SX1231H offers the unique advantage of programmable narrow-band and wide-band communication modes without the need to modify external components. The SX1231H is optimized for low power consumption while offering high RF output power and channelized operation. TrueRF™ technology enables a low-cost external component count (elimination of the SAW filter) whilst still satisfying ETSI and FCC regulations.

APPLICATIONS

- ◆ Automated Meter Reading
- ◆ Wireless Sensor Networks
- ◆ Home and Building Automation
- ◆ Wireless Alarm and Security Systems
- ◆ Industrial Monitoring and Control
- ◆ Wireless M-BUS

MARKETS

- ◆ Europe: EN 300-220-1
- ◆ North America: FCC Part 15.247, 15.249, 15.231

KEY PRODUCT FEATURES

- ◆ **+20 dBm - 100 mW Power Output Capability**
- ◆ High Sensitivity: down to -120 dBm at 1.2 kbps
- ◆ High Selectivity: 16-tap FIR Channel Filter
- ◆ Bullet-proof front end: IIP3 = -18 dBm, IIP2 = +35 dBm, 80 dB Blocking Immunity, no Image Frequency response
- ◆ Low current: Rx = 16 mA, 100nA register retention
- ◆ Programmable Pout: -18 to +20 dBm in 1dB steps
- ◆ Constant RF performance over voltage range of chip
- ◆ FSK Bit rates up to 300 kb/s
- ◆ Fully integrated synthesizer with a resolution of 61 Hz
- ◆ FSK, GFSK, MSK, GMSK and OOK modulations
- ◆ Built-in Bit Synchronizer performing Clock Recovery
- ◆ Incoming Sync Word Recognition
- ◆ 115 dB+ Dynamic Range RSSI
- ◆ Automatic RF Sense with ultra-fast AFC
- ◆ Packet engine with CRC-16, AES-128, 66-byte FIFO
- ◆ Built-in temperature sensor

ORDERING INFORMATION

Part Number	Delivery	MOQ / Multiple
SX1231HIMLTRT	Tape & Reel	3000 pieces

- ◆ QFN 24 Package - Operating Range [-40;+85°C]
- ◆ Pb-free, Halogen free, RoHS/WEEE compliant product

Table of Contents

	Page
1. General Description	8
1.1. Simplified Block Diagram	8
1.2. Pin and Marking Diagram.....	9
1.3. Pin Description	10
2. Electrical Characteristics.....	11
2.1. ESD Notice.....	11
2.2. Absolute Maximum Ratings	11
2.3. Operating Range.....	11
2.4. Chip Specification	12
2.4.1. Power Consumption	12
2.4.2. Frequency Synthesis.....	12
2.4.3. Receiver	13
2.4.4. Transmitter	14
2.4.5. Digital Specification	15
3. Chip Description.....	16
3.1. Power Supply Strategy.....	16
3.2. Frequency Synthesis.....	16
3.2.1. Reference Oscillator	16
3.2.2. CLKOUT Output	17
3.2.3. PLL Architecture.....	17
3.2.4. Lock Time.....	18
3.2.5. Lock Detect Indicator.....	18
3.3. Transmitter Description	19
3.3.1. Architecture Description	19
3.3.2. Bit Rate Setting	19
3.3.3. FSK Modulation.....	20
3.3.4. OOK Modulation.....	20
3.3.5. Modulation Shaping.....	21
3.3.6. Power Amplifiers	21
3.3.7. High Power Settings	22
3.3.8. Output Power Summary	22
3.3.9. Over Current Protection	22
3.4. Receiver Description	23
3.4.1. Block Diagram	23
3.4.2. LNA - Single to Differential Buffer	23
3.4.3. Automatic Gain Control	24
3.4.4. Continuous-Time DAGC.....	25
3.4.5. Quadrature Mixer - ADCs - Decimators.....	26
3.4.6. Channel Filter	26
3.4.7. DC Cancellation	27

3.4.8. Complex Filter - OOK	27
3.4.9. RSSI	27
3.4.10. Cordic	28
3.4.11. FSK Demodulator	29
3.4.12. OOK Demodulator	29
3.4.13. Bit Synchronizer	31
3.4.14. Frequency Error Indicator.....	31
3.4.15. Automatic Frequency Correction.....	32
3.4.16. Optimized Setup for Low Modulation Index Systems.....	33
3.4.17. Temperature Sensor	34
3.4.18. Timeout Function.....	34
4. Operating Modes	35
4.1. Basic Modes.....	35
4.2. Automatic Sequencer and Wake-Up Times	35
4.2.1. Transmitter Startup Time	36
4.2.2. Tx Start Procedure	36
4.2.3. Receiver Startup Time.....	36
4.2.4. Rx Start Procedure	38
4.2.5. Optimized Frequency Hopping Sequences.....	38
4.3. Listen Mode.....	39
4.3.1. Timings	39
4.3.2. Criteria.....	40
4.3.3. End of Cycle Actions	40
4.3.4. Stopping Listen Mode.....	41
4.3.5. RC Timer Accuracy	41
4.4. AutoModes	42
5. Data Processing.....	43
5.1. Overview	43
5.1.1. Block Diagram	43
5.1.2. Data Operation Modes	43
5.2. Control Block Description.....	44
5.2.1. SPI Interface.....	44
5.2.2. FIFO	45
5.2.3. Sync Word Recognition.....	46
5.2.4. Packet Handler.....	47
5.2.5. Control.....	47
5.3. Digital IO Pins Mapping.....	47
5.3.1. DIO Pins Mapping in Continuous Mode	48
5.3.2. DIO Pins Mapping in Packet Mode	48
5.4. Continuous Mode	49
5.4.1. General Description.....	49
5.4.2. Tx Processing.....	49

5.4.3. Rx Processing	50
5.5. Packet Mode	50
5.5.1. General Description.....	50
5.5.2. Packet Format	51
5.5.3. Tx Processing (without AES).....	53
5.5.4. Rx Processing (without AES)	54
5.5.5. AES	54
5.5.6. Handling Large Packets	56
5.5.7. Packet Filtering.....	56
5.5.8. DC-Free Data Mechanisms.....	58
6. Configuration and Status Registers	60
6.1. General Description	60
6.2. Common Configuration Registers	63
6.3. Transmitter Registers	66
6.4. Receiver Registers.....	67
6.5. IRQ and Pin Mapping Registers.....	69
6.6. Packet Engine Registers.....	71
6.7. Temperature Sensor Registers	74
6.8. Test Registers	74
7. Application Information	75
7.1. Crystal Resonator Specification	75
7.2. Reset of the Chip	75
7.2.1. POR.....	75
7.2.2. Manual Reset	76
7.3. Reference Design	76
8. Packaging Information	79
8.1. Package Outline Drawing.....	79
8.2. Recommended Land Pattern	79
8.3. Thermal Impedance	80
8.4. Tape & Reel Specification.....	80
9. Revision History	81

Index of Figures
Page

Figure 1. Block Diagram	8
Figure 2. Pin Diagram	9
Figure 3. Marking Diagram	9
Figure 4. TCXO Connection	16
Figure 5. Transmitter Block Diagram	19
Figure 6. Output Power Curves	22
Figure 7. Receiver Block Diagram	23
Figure 8. AGC Thresholds Settings	24
Figure 9. RSSI Dynamic Curve	28
Figure 10. Cordic Extraction	28
Figure 11. OOK Peak Demodulator Description	29
Figure 12. Floor Threshold Optimization	30
Figure 13. Bit Synchronizer Description	31
Figure 14. FEI Process	32
Figure 15. Optimized AFC (AfcLowBetaOn=1)	33
Figure 16. Temperature Sensor Response	34
Figure 17. Tx Startup, FSK and OOK	36
Figure 18. Rx Startup - No AGC, no AFC	37
Figure 19. Rx Startup - AGC, no AFC	37
Figure 20. Rx Startup - AGC and AFC	37
Figure 21. Listen Mode Sequence (no wanted signal is received)	39
Figure 22. Listen Mode Sequence (wanted signal is received)	41
Figure 23. Auto Modes of Packet Handler	42
Figure 24. SX1231H Data Processing Conceptual View	43
Figure 25. SPI Timing Diagram (single access)	44
Figure 26. FIFO and Shift Register (SR)	45
Figure 27. FifoLevel IRQ Source Behavior	46
Figure 28. Sync Word Recognition	47
Figure 29. Continuous Mode Conceptual View	49
Figure 30. Tx Processing in Continuous Mode	49
Figure 31. Rx Processing in Continuous Mode	50
Figure 32. Packet Mode Conceptual View	51
Figure 33. Fixed Length Packet Format	52
Figure 34. Variable Length Packet Format	52
Figure 35. Unlimited Length Packet Format	53
Figure 36. CRC Implementation	58
Figure 37. Manchester Encoding/Decoding	58
Figure 38. Data Whitening	59
Figure 39. POR Timing Diagram	75
Figure 40. Manual Reset Timing Diagram	76
Figure 41. +13dBm Schematic	76

Figure 42. +17/20dBm Schematic	77
Figure 43. Package Outline Drawing	79
Figure 44. Recommended Land Pattern	79
Figure 45. Tape & Reel Specification	80

Index of Tables

	Page
Table 1. SX1231H Pinouts	10
Table 2. Absolute Maximum Ratings	11
Table 3. Operating Range	11
Table 4. Power Consumption Specification	12
Table 5. Frequency Synthesizer Specification	12
Table 6. Receiver Specification	13
Table 7. Transmitter Specification	14
Table 8. Digital Specification	15
Table 9. Bit Rate Examples	20
Table 10. Power Amplifier Mode Selection Truth Table	21
Table 11. High Power Settings	22
Table 12. LNA Gain Settings	23
Table 13. Receiver Performance Summary	25
Table 14. Available RxBw Settings	26
Table 15. Available DCC Cutoff Frequencies	27
Table 16. Basic Transceiver Modes	35
Table 17. Range of Durations in Listen Mode	39
Table 18. Signal Acceptance Criteria in Listen Mode	40
Table 19. End of Listen Cycle Actions	40
Table 20. Status of FIFO when Switching Between Different Modes of the Chip	46
Table 21. DIO Mapping, Continuous Mode	48
Table 22. DIO Mapping, Packet Mode	48
Table 23. Registers Summary	60
Table 24. Common Configuration Registers	63
Table 25. Transmitter Registers	66
Table 26. Receiver Registers	67
Table 27. IRQ and Pin Mapping Registers	69
Table 28. Packet Engine Registers	71
Table 29. Temperature Sensor Registers	74
Table 30. Test Registers	74
Table 31. Crystal Specification	75
Table 32. +13dBm BOM	77
Table 33. +17/20dBm BOM	77
Table 34. Revision History	81

Acronyms

BOM	Bill Of Materials	LSB	Least Significant Bit
BR	Bit Rate	MSB	Most Significant Bit
BW	Bandwidth	NRZ	Non Return to Zero
CCITT	Comité Consultatif International Téléphonique et Télégraphique - ITU	OOK	On Off Keying
CRC	Cyclic Redundancy Check	PA	Power Amplifier
DAC	Digital to Analog Converter	PCB	Printed Circuit Board
ETSI	European Telecommunications Standards Institute	PLL	Phase-Locked Loop
FCC	Federal Communications Commission	POR	Power On Reset
Fdev	Frequency Deviation	RBW	Resolution BandWidth
FIFO	First In First Out	RF	Radio Frequency
FIR	Finite Impulse Response	RSSI	Received Signal Strength Indicator
FS	Frequency Synthesizer	Rx	Receiver
FSK	Frequency Shift Keying	SAW	Surface Acoustic Wave
GUI	Graphical User Interface	SPI	Serial Peripheral Interface
IC	Integrated Circuit	SR	Shift Register
ID	IDentificator	Stby	Standby
IF	Intermediate Frequency	Tx	Transmitter
IRQ	Interrupt ReQuest	uC	Microcontroller
ITU	International Telecommunication Union	VCO	Voltage Controlled Oscillator
LFSR	Linear Feedback Shift Register	XO	Crystal Oscillator
LNA	Low Noise Amplifier	XOR	eXclusive OR
LO	Local Oscillator		

This product datasheet contains a detailed description of the SX1231H performance and functionality. Please consult the Semtech website for the latest updates or errata.

1. General Description

The SX1231H is a single-chip integrated circuit ideally suited for today's high performance ISM band RF applications. The SX1231H's advanced features set, including state of the art packet engine greatly simplifies system design whilst the high level of integration reduces the external BOM to a handful of passive decoupling and matching components. It is intended for use as high-performance, low-cost FSK and OOK RF transceiver for robust frequency agile, half-duplex bi-directional RF links, and where stable and constant RF performance is required over the full operating range of the device down to 2.4V.

The SX1231H is intended for applications over a wide frequency range, including the 433 MHz and 868 MHz European and the 902-928 MHz North American ISM bands. Coupled with a link budget in excess of 140 dB, the advanced system features of the SX1231H include a 66 byte TX/RX FIFO, configurable automatic packet handler, listen mode, temperature sensor and configurable DIOs which greatly enhance system flexibility whilst at the same time significantly reducing MCU requirements.

The SX1231H complies with both ETSI and FCC regulatory requirements and is available in a 5x 5 mm QFN 24 lead package

1.1. Simplified Block Diagram

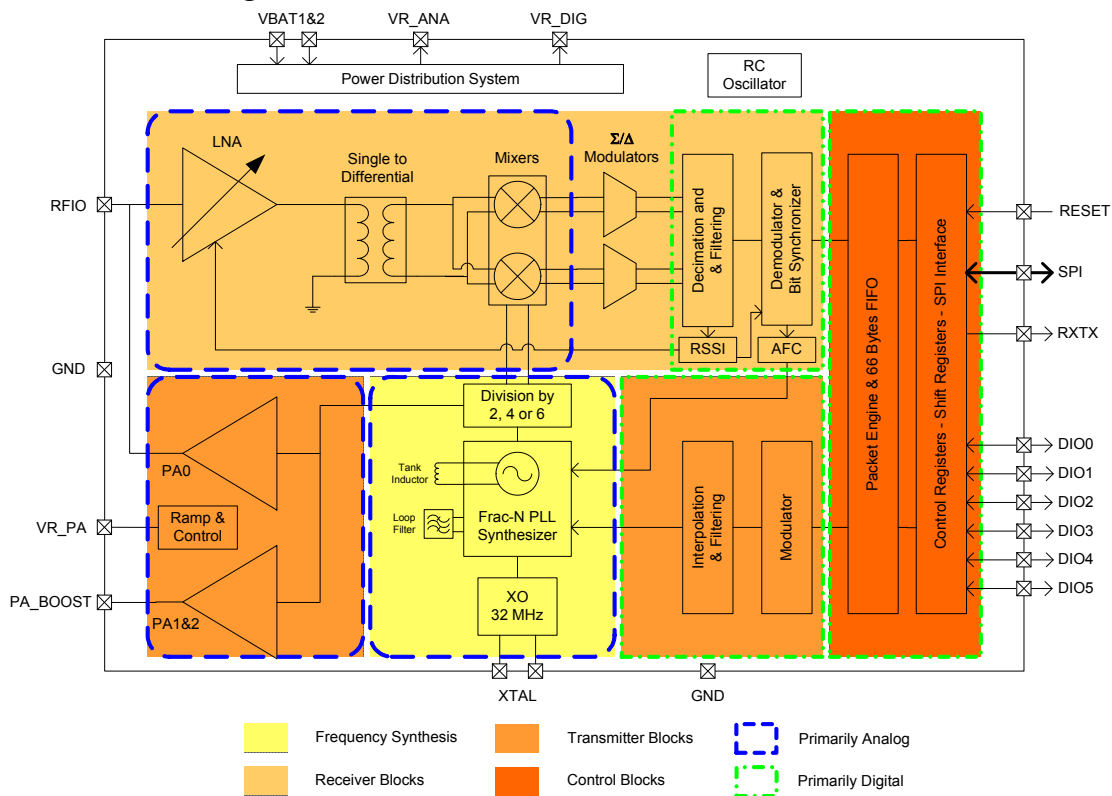


Figure 1. Block Diagram

1.2. Pin and Marking Diagram

The following diagram shows the pin arrangement of the QFN package, top view.

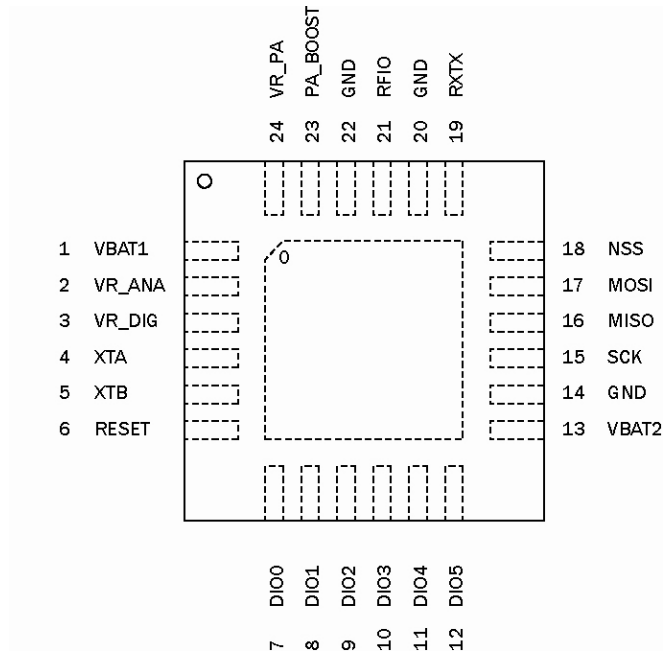


Figure 2. Pin Diagram

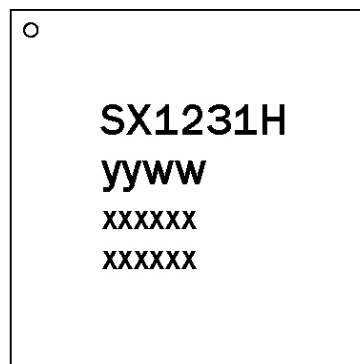


Figure 3. Marking Diagram

Notes yyww refers to the date code
xxxxxx refers to the lot number

1.3. Pin Description

Table 1 SX1231H Pinouts

Number	Name	Type	Description
0	GROUND	-	Exposed ground pad
1	VBAT1	-	Supply voltage
2	VR_ANA	-	Regulated supply voltage for analogue circuitry
3	VR_DIG	-	Regulated supply voltage for digital blocks
4	XTA	I/O	XTAL connection
5	XTB	I/O	XTAL connection
6	RESET	I/O	Reset trigger input
7	DIO0	I/O	Digital I/O, software configured
8	DIO1/DCLK	I/O	Digital I/O, software configured
9	DIO2/DATA	I/O	Digital I/O, software configured
10	DIO3	I/O	Digital I/O, software configured
11	DIO4	I/O	Digital I/O, software configured
12	DIO5	I/O	Digital I/O, software configured
13	VBAT2	-	Supply voltage
14	GND	-	Ground
15	SCK	I	SPI Clock input
16	MISO	O	SPI Data output
17	MOSI	I	SPI Data input
18	NSS	I	SPI Chip select input
19	RXTX	O	Rx/Tx switch control: high in Tx
20	GND	-	Ground
21	RFIO	I/O	RF input / output
22	GND	-	Ground
23	PA_BOOST	O	Optional high-power PA output
24	VR_PA	-	Regulated supply for the PA

Note PA_BOOST can be left floating if unused

2. Electrical Characteristics

2.1. ESD Notice

The SX1231H is a high performance radio frequency device. It satisfies:

- ◆ Class 2 of the JEDEC standard JESD22-A114-B (Human Body Model) on all pins.
- ◆ Class B of the JEDEC standard JESD22-A115-A (Machine Model) on all pins.
- ◆ Class IV of the JEDEC standard JESD22-C101C (Charged Device Model) on pins 2-3-21-23-24, Class III on all other pins.



It should thus be handled with all the necessary ESD precautions to avoid any permanent damage.

2.2. Absolute Maximum Ratings

Stresses above the values listed below may cause permanent device failure. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Table 2 Absolute Maximum Ratings

Symbol	Description	Min	Max	Unit
VDDmr	Supply Voltage	-0.5	3.9	V
Tmr	Temperature	-55	+115	° C
Tj	Junction temperature	-	+125	° C
Pmr	RF Input Level	-	+6	dBm
DC_20dBm	Duty Cycle of transmission at +20dBm output	-	1	%
VSWR_20dBm	Maximum VSWR at antenna port	-	3:1	-

2.3. Operating Range

Table 3 Operating Range

Symbol	Description	Min	Max	Unit
VDDop	Supply voltage	2.4	3.6	V
Top	Operational temperature range	-40	+85	°C
Clop	Load capacitance on digital ports	-	25	pF
ML	RF Input Level	-	0	dBm

2.4. Chip Specification

The tables below give the electrical specifications of the transceiver under the following conditions: Supply voltage VBAT1=VBAT2=VDD=3.3 V, temperature = 25 °C, FXOSC = 32 MHz, F_{RF} = 915 MHz, P_{out} = +13dBm, 2-level FSK modulation without pre-filtering, FDA = 5 kHz, Bit Rate = 4.8 kb/s and terminated in a matched 50 Ohm impedance, unless otherwise specified.

Note Unless otherwise specified, the performances in the other frequency bands are similar or better.

2.4.1. Power Consumption

Table 4 Power Consumption Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
IDDSL	Supply current in Sleep mode		-	0.1	1	uA
IDDIDLE	Supply current in Idle mode	RC oscillator enabled	-	1.2	-	uA
IDDST	Supply current in Standby mode	Crystal oscillator enabled	-	1.25	1.5	mA
IDDFS	Supply current in Synthesizer mode		-	9	-	mA
IDDR	Supply current in Receive mode		-	16	-	mA
IDDT	Supply current in Transmit mode with appropriate matching, stable across VDD range	RFOP = +20 dBm, on PA_BOOST	-	130	-	mA
		RFOP = +17 dBm, on PA_BOOST	-	95	-	mA
		RFOP = +13 dBm, on RFIO pin	-	45	-	mA
		RFOP = +10 dBm, on RFIO pin	-	33	-	mA
		RFOP = 0 dBm, on RFIO pin	-	20	-	mA
		RFOP = -1 dBm, on RFIO pin	-	16	-	mA

2.4.2. Frequency Synthesis

Table 5 Frequency Synthesizer Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
FR	Synthesizer Frequency Range	Programmable	290	-	340	MHz
			431	-	510	MHz
			862	-	1020	MHz
FXOSC	Crystal oscillator frequency	See section 7.1	-	32	-	MHz
TS_OSC	Crystal oscillator wake-up time		-	250	500	us
TS_FS	Frequency synthesizer wake-up time to PLLock signal	From Standby mode	-	80	150	us
TS_HOP	Frequency synthesizer hop time at most 10 kHz away from the target	200 kHz step	-	20	-	us
		1 MHz step	-	20	-	us
		5 MHz step	-	50	-	us
		7 MHz step	-	50	-	us
		12 MHz step	-	80	-	us
		20 MHz step	-	80	-	us
		25 MHz step	-	80	-	us

FSTEP	Frequency synthesizer step	$FSTEP = FXOSC/2^{19}$	-	61.0	-	Hz
FRC	RC Oscillator frequency	After calibration	-	62.5	-	kHz
BRF	Bit rate, FSK	Programmable	1.2	-	300	kbps
BRO	Bit rate, OOK	Programmable	1.2	-	32.768	kbps
FDA	Frequency deviation, FSK	Programmable $FDA + BRF/2 \leq 500$ kHz	0.6	-	300	kHz

2.4.3. Receiver

All receiver tests are performed with $RxBw = 10$ kHz (Single Side Bandwidth) as programmed in $RegRxBw$, receiving a PN15 sequence with a BER of 0.1% (Bit Synchronizer is enabled), unless otherwise specified. The LNA impedance is set to 200 Ohms, by setting bit $LnaZin$ in $RegLna$ to 1. Blocking tests are performed with an unmodulated interferer. The wanted signal power for the Blocking Immunity, ACR, IIP2, IIP3 and AMR tests is set 3 dB above the nominal sensitivity level.

Table 6 Receiver Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
RFS_F	FSK sensitivity, highest LNA gain	FDA = 5 kHz, BR = 1.2 kb/s	-	-118	-	dBm
		FDA = 5 kHz, BR = 4.8 kb/s	-	-114	-	dBm
		FDA = 40 kHz, BR = 38.4 kb/s	-	-105	-	dBm
		FDA = 5 kHz, BR = 1.2 kb/s *	-	-120	-	dBm
RFS_O	OOK sensitivity, highest LNA gain	BR = 4.8 kb/s	-	-112	-109	dBm
CCR	Co-Channel Rejection		-13	-10	-	dB
ACR	Adjacent Channel Rejection	Offset = +/- 25 kHz	-	42	-	dB
		Offset = +/- 50 kHz	37	42	-	dB
BI	Blocking Immunity	Offset = +/- 1 MHz	-	66	-	dB
		Offset = +/- 2 MHz	-	71	-	dB
		Offset = +/- 10 MHz	-	79	-	dB
	Blocking Immunity Wanted signal at sensitivity +16dB	Offset = +/- 1 MHz	-	62	-	dB
		Offset = +/- 2 MHz	-	65	-	dB
		Offset = +/- 10 MHz	-	73	-	dB
AMR	AM Rejection , AM modulated interferer with 100% modulation depth, fm = 1 kHz, square	Offset = +/- 1 MHz	-	66	-	dB
		Offset = +/- 2 MHz	-	71	-	dB
		Offset = +/- 10 MHz	-	79	-	dB
IIP2	2nd order Input Intercept Point Unwanted tones are 20 MHz above the LO	Lowest LNA gain	-	+75	-	dBm
		Highest LNA gain	-	+35	-	dBm

IIP3	3rd order Input Intercept point Unwanted tones are 1MHz and 1.995 MHz above the LO	Lowest LNA gain Highest LNA gain	- -23	+20 -18	- -	dBm dBm
BW_SSB	Single Side channel filter BW	Programmable	2.6	-	500	kHz
IMR_OOK	Image rejection in OOK mode	Wanted signal level = -106 dBm	27	30	-	dB
TS_RE	Receiver wake-up time, from PLL locked state to <i>RxReady</i>	RxBw = 10 kHz, BR = 4.8 kb/s RxBw = 200 kHz, BR = 100 kb/s	- -	1.7 96	- -	ms us
TS_RE_AGC	Receiver wake-up time, from PLL locked state, AGC enabled	RxBw = 10 kHz, BR = 4.8 kb/s RxBw = 200 kHz, BR = 100 kb/s	-	3.0 163		ms us
TS_RE_AGC & AFC	Receiver wake-up time, from PLL lock state, AGC and AFC enabled	RxBw = 10 kHz, BR = 4.8 kb/s RxBw = 200 kHz, BR = 100 kb/s		4.8 265		ms us
TS_FEI	FEI sampling time	Receiver is ready	-	4.T _{bit}	-	-
TS_AFC	AFC Response Time	Receiver is ready	-	4.T _{bit}	-	-
TS_RSSI	RSSI Response Time	Receiver is ready	-	2.T _{bit}	-	-
DR_RSSI	RSSI Dynamic Range	AGC enabled	Min Max	- -115 0	- -	dBm dBm

* Set *SensitivityBoost* in *RegTestLna* to 0x2D to reduce the noise floor in the receiver

2.4.4. Transmitter

Table 7 Transmitter Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
RF_OP	RF output power in 50 ohms On RFIO pin	Programmable with 1dB steps Max Min	- -	+13 -18	- -	dBm dBm
RF_OPH	Max RF output power, on PA_BOOST pin	With external match to 50 ohms	-	+20	-	dBm
Δ RF_OP	RF output power stability	From VDD=2.4V to 3.6V	-	+/-0.3	-	dB
PHN	Transmitter Phase Noise	50 kHz Offset from carrier 868 / 915 MHz bands 434 / 315 MHz bands	- -	-95 -99	- -	dBc/ Hz
ACP	Transmitter adjacent channel power (measured at 25 kHz off- set)	BT=0.5 . Measurement conditions as defined by EN 300 220-1 V2.1.1	-	-	-37	dBm
TS_TR	Transmitter wake up time, to the first rising edge of DCLK	Frequency Synthesizer enabled, <i>PaRamp</i> = 10 us, BR = 4.8 kb/s.	-	120	-	us

2.4.5. Digital Specification

Conditions: Temp = 25°C, VDD = 3.3V, FXOSC = 32 MHz, unless otherwise specified.

Table 8 Digital Specification

Symbol	Description	Conditions	Min	Typ	Max	Unit
V _{IH}	Digital input level high		0.8	-	-	VDD
V _{IL}	Digital input level low		-	-	0.2	VDD
V _{OH}	Digital output level high	I _{max} = 1 mA	0.9	-	-	VDD
V _{OL}	Digital output level low	I _{max} = -1 mA	-	-	0.1	VDD
F _{SCK}	SCK frequency		-	-	10	MHz
t _{ch}	SCK high time		50	-	-	ns
t _{cl}	SCK low time		50	-	-	ns
t _{rise}	SCK rise time		-	5	-	ns
t _{fall}	SCK fall time		-	5	-	ns
t _{setup}	MOSI setup time	from MOSI change to SCK rising edge	30	-	-	ns
t _{hold}	MOSI hold time	from SCK rising edge to MOSI change	60	-	-	ns
t _{nsetup}	NSS setup time	from NSS falling edge to SCK rising edge	30	-	-	ns
t _{nhold}	NSS hold time	from SCK falling edge to NSS rising edge, normal mode	30	-	-	ns
t _{nhigh}	NSS high time between SPI accesses		20	-	-	ns
T_DATA	DATA hold and setup time		250	-	-	ns

3. Chip Description

This section describes in depth the architecture of the SX1231H low-power, highly integrated transceiver.

3.1. Power Supply Strategy

The SX1231H employs an advanced power supply scheme, which provides stable operating characteristics over the full temperature and voltage range of operation. This includes the full output power of +20dBm maintained from 2.4 to 3.6V.

The SX1231H can be powered from any low-noise voltage source via pins VBAT1 and VBAT2. Decoupling capacitors should be connected, as suggested in the reference design, on VR_PA, VR_DIG and VR_ANA pins to ensure a correct operation of the built-in voltage regulators.

3.2. Frequency Synthesis

The LO generation on the SX1231H is based on a state-of-the-art fractional-N PLL. The PLL is fully integrated with automatic calibration.

3.2.1. Reference Oscillator

The crystal oscillator is the main timing reference of the SX1231H. It is used as a reference for the frequency synthesizer and as a clock for the digital processing.

The XO startup time, TS_OSC, depends on the actual XTAL being connected on pins XTA and XTB. When using the built-in sequencer, the SX1231H optimizes the startup time and automatically triggers the PLL when the XO signal is stable. To manually control the startup time, the user should either wait for TS_OSC max, or monitor the signal CLKOUT which will only be made available on the output buffer when a stable XO oscillation is achieved.

An external clock can be used to replace the crystal oscillator, for instance a tight tolerance TCXO. To do so, bit 4 at address 0x59 should be set to 1, and the external clock has to be provided on XTA (pin 4). XTB (pin 5) should be left open. The peak-peak amplitude of the input signal must never exceed 1.8 V. Please consult your TCXO supplier for an appropriate value of decoupling capacitor, C_D.

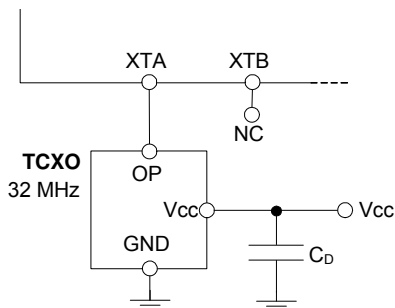


Figure 4. TCXO Connection

3.2.2. CLKOUT Output

The reference frequency, or a fraction of it, can be provided on DIO5 (pin 12) by modifying bits *ClkOut* in *RegDioMapping2*. Two typical applications of the CLKOUT output include:

- ◆ To provide a clock output for a companion processor, thus saving the cost of an additional oscillator. CLKOUT can be made available in any operation mode except Sleep mode and is automatically enabled at power on reset.
- ◆ To provide an oscillator reference output. Measurement of the CLKOUT signal enables simple software trimming of the initial crystal tolerance.

Note to minimize the current consumption of the SX1231H, please ensure that the CLKOUT signal is disabled when not required.

3.2.3. PLL Architecture

The frequency synthesizer generating the LO frequency for both the receiver and the transmitter is a fractional-N sigma-delta PLL. The PLL incorporates a third order loop capable of fast auto-calibration, and it has a fast switching-time. The VCO and the loop filter are both fully integrated, removing the need for an external tight-tolerance, high-Q inductor in the VCO tank circuit.

3.2.3.1. VCO

The VCO runs at 2, 4 or 6 times the RF frequency (respectively in the 915, 434 and 315 MHz bands) to reduce any LO leakage in receiver mode, to improve the quadrature precision of the receiver, and to reduce the pulling effects on the VCO during transmission.

The VCO calibration is fully automated. A coarse adjustment is carried out at power on reset, and a fine tuning is performed each time the SX1231H PLL is activated. Automatic calibration times are fully transparent to the end-user, as their processing time is included in the *TS_TE* and *TS_RE* specifications.

3.2.3.2. PLL Bandwidth

The bandwidth of the SX1231H Fractional-N PLL is wide enough to allow for:

- ◆ High speed FSK modulation, up to 300 kb/s, inside the PLL bandwidth
- ◆ Very fast PLL lock times, enabling both short startup and fast hop times required for frequency agile applications

3.2.3.3. Carrier Frequency and Resolution

The SX1231H PLL embeds a 19-bit sigma-delta modulator and its frequency resolution, constant over the whole frequency range, and is given by:

$$F_{STEP} = \frac{F_{XOSC}}{2^{19}}$$

The carrier frequency is programmed through *RegFrf*, split across addresses 0x07 to 0x09:

$$F_{RF} = F_{STEP} \times Frf(23,0)$$

Note The *Frf* setting is split across 3 bytes. A change in the center frequency will only be taken into account when the least significant byte *FrfLsb* in *RegFrfLsb* is written. This allows for more complex modulation schemes such as *m*-ary FSK, where frequency modulation is achieved by changing the programmed RF frequency.

3.2.4. Lock Time

PLL lock time TS_FS is a function of a number of technical factors, such as synthesized frequency, frequency step, etc. When using the built-in sequencer, the SX1231H optimizes the startup time and automatically starts the receiver or the transmitter when the PLL has locked. To manually control the startup time, the user should either wait for TS_FS max given in the specification, or monitor the signal PLL lock detect indicator, which is set when the PLL has is within its locking range.

When performing an AFC, which usually corrects very small frequency errors, the PLL response time is approximately:

$$T_{PLLAFC} = \frac{5}{PLLBW}$$

In a frequency hopping scheme, the timings TS_HOP given in the table of specifications give an order of magnitude for the expected lock times.

3.2.5. Lock Detect Indicator

A lock indication signal can be made available on some of the DIO pins, and is toggled high when the PLL reaches its locking range. Please refer to Table 21 and Table 22 to map this interrupt to the desired pins.

Note The lock detect block may indicate an unlock condition (signal toggling low) when the transmitter is FSK modulated with large frequency deviation settings.

3.3. Transmitter Description

The transmitter of SX1231H comprises the frequency synthesizer, modulator and power amplifier blocks.

3.3.1. Architecture Description

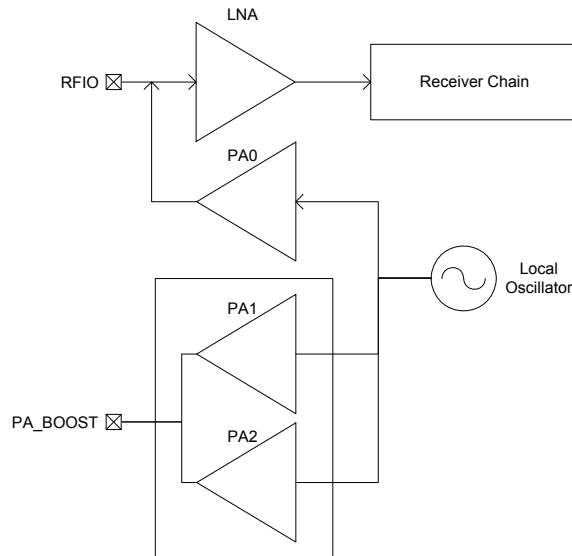


Figure 5. Transmitter Block Diagram

3.3.2. Bit Rate Setting

When using the SX1231H in Continuous mode, the data stream to be transmitted can be input directly to the modulator via pin 9 (DIO2/DATA) in an asynchronous manner, unless Gaussian filtering is used, in which case the DCLK signal on pin 10 (DIO1/DCLK) is used to synchronize the data stream. See section 3.3.5 for details on the Gaussian filter.

In Packet mode or in Continuous mode with Gaussian filtering enabled (refer to section 5.5 for details), the Bit Rate (BR) is controlled by bits *BitRate* in *RegBitrate*:

$$BR = \frac{F_{XOSC}}{BitRate}$$

Amongst others, the following Bit Rates are accessible:

Table 9 Bit Rate Examples

Type	BitRate (15:8)	BitRate (7:0)	(G)FSK (G)MSK	OOK	Actual BR (b/s)
Classical modem baud rates (multiples of 1.2 kbps)	0x68	0x2B	1.2 kbps	1.2 kbps	1200.015
	0x34	0x15	2.4 kbps	2.4 kbps	2400.060
	0x1A	0x0B	4.8 kbps	4.8 kbps	4799.760
	0x0D	0x05	9.6 kbps	9.6 kbps	9600.960
	0x06	0x83	19.2 kbps	19.2 kbps	19196.16
	0x03	0x41	38.4 kbps		38415.36
	0x01	0xA1	76.8 kbps		76738.60
	0x00	0xD0	153.6 kbps		153846.1
Classical modem baud rates (multiples of 0.9 kbps)	0x02	0x2C	57.6 kbps		57553.95
	0x01	0x16	115.2 kbps		115107.9
Round bit rates (multiples of 12.5, 25 and 50 kbps)	0x0A	0x00	12.5 kbps	12.5 kbps	12500.00
	0x05	0x00	25 kbps	25 kbps	25000.00
	0x02	0x80	50 kbps		50000.00
	0x01	0x40	100 kbps		100000.0
	0x00	0xD5	150 kbps		150234.7
	0x00	0xA0	200 kbps		200000.0
	0x00	0x80	250 kbps		250000.0
	0x00	0x6B	300 kbps		299065.4
Watch Xtal frequency	0x03	0xD1	32.768 kbps	32.768 kbps	32753.32

3.3.3. FSK Modulation

FSK modulation is performed inside the PLL bandwidth, by changing the fractional divider ratio in the feedback loop of the PLL. The large resolution of the sigma-delta modulator, allows for very narrow frequency deviation. The frequency deviation FDEV is given by:

$$F_{DEV} = F_{STEP} \times Fdev(13,0)$$

To ensure a proper modulation, the following limit applies:

$$F_{DEV} + \frac{BR}{2} \leq 500kHz$$

Note no constraint applies to the modulation index of the transmitter, but the frequency deviation must exceed 600 Hz.

3.3.4. OOK Modulation

OOK modulation is applied by switching on and off the Power Amplifier. Digital control and smoothing are available to improve the transient power response of the OOK transmitter.

3.3.5. Modulation Shaping

Modulation shaping can be applied in both OOK and FSK modulation modes, to improve the narrowband response of the transmitter. Both shaping features are controlled with *PaRamp* bits in *RegPaRamp*.

- ◆ In FSK mode, a Gaussian filter with $BT = 0.3, 0.5$ or 1 is used to filter the modulation stream, at the input of the sigma-delta modulator. If the Gaussian filter is enabled when the SX1231H is in Continuous mode, DCLK signal on pin 10 (DIO1/DCLK) will trigger an interrupt on the uC each time a new bit has to be transmitted. Please refer to section 5.4.2 for details.
- ◆ When OOK modulation is used, the PA bias voltages are ramped up and down smoothly when the PA is turned on and off, to reduce spectral splatter.

Note the transmitter must be restarted if the *PaRamp* setting is changed, in order to recalibrate the built-in filter.

3.3.6. Power Amplifiers

Three power amplifier blocks are embedded in the SX1231H. The first one, herein referred to as PA0, can generate up to +13 dBm into a 50 Ohm load. PA0 shares a common front-end pin RFIO (pin 21) with the receiver LNA.

PA1 and PA2 are both connected to pin PA_BOOST (pin 23), allowing for two distinct power ranges:

- ◆ A low power mode, where $-2 \text{ dBm} < P_{out} < 13 \text{ dBm}$, with PA1 enabled
- ◆ A higher power mode, when PA1 and PA2 are combined, providing up to +20 dBm to a matched load.

When PA1 and PA2 are combined to deliver +20 dBm to the antenna, a specific impedance matching / harmonic filtering design is required to ensure impedance transformation and regulatory compliance.

All PA settings are controlled by *RegPaLevel*, and the truth table of settings is given in Table 10.

Table 10 Power Amplifier Mode Selection Truth Table

<i>Pa0On</i>	<i>Pa1On</i>	<i>Pa2On</i>	Mode	Power Range	Pout Formula
1	0	0	PA0 output on pin RFIO	-18 to +13 dBm	-18 dBm + <i>OutputPower</i>
0	1	0	PA1 enabled on pin PA_BOOST	-2 to +13 dBm	-18 dBm + <i>OutputPower</i>
0	1	1	PA1 and PA2 combined on pin PA_BOOST	+2 to +17 dBm	-14 dBm + <i>OutputPower</i>
0	1	1	PA1+PA2 on PA_BOOST with high output power +20dBm settings (see 3.3.7)	+5 to +20 dBm	-11 dBm + <i>OutputPower</i>
Other combinations			Reserved		

Notes - To ensure correct operation at the highest power levels, please make sure to adjust the Over Current Protection Limit accordingly in *RegOcp*, except above +18dBm where it must be disabled

- If PA_BOOST pin is not used (+13dBm applications and less), the pin can be left floating.

3.3.7. High Power Settings

The SX1231H has a high power +20 dBm capability on PA_BOOST pin, with the following settings:

Table 11 High Power Settings

Register	Address	Value for High Power	Value for Rx or PA0 use	Description
RegOcp	0x13	0x0F	0x1x	OCP control
RegTestPa1	0x5A	0x5D	0x55	High power PA control
RegTestPa2	0x5C	0x7C	0x70	High power PA control

Note High Power settings MUST be turned off when using PA0, and in Receive mode

The Duty Cycle of transmission at +20dBm is limited to 1%, with a maximum VSWR of 3:1 at antenna port, over the standard operating range [-40;+85°C]. For any other operating condition, contact your Semtech representative.

3.3.8. Output Power Summary

The curves below summarize the possible PA options on the SX1231H:

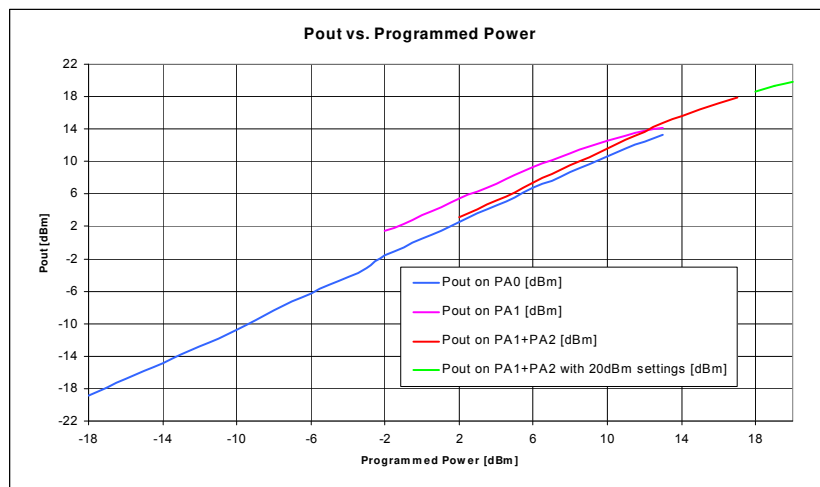


Figure 6. Output Power Curves

3.3.9. Over Current Protection

An over current protection block is built-in the chip. It helps preventing surge currents required when the transmitter is used at its highest power levels, thus protecting the battery that may power the application. The current clamping value is controlled by *OcpTrim* bits in *RegOcp*, and is calculated with the following formula:

$$I_{max} = 45 + 5 \times OcpTrim(mA)$$

Note *I_{max}* sets a limit on the current drain of the Power Amplifier only, hence the maximum current drain of the SX1231H is equal to *I_{max}* + *I_{FS}*

3.4. Receiver Description

The SX1231H features a digital receiver with the analog to digital conversion process being performed directly following the LNA-Mixers block. The zero-IF receiver is able to handle (G)FSK and (G)MSK modulation. ASK and OOK modulation is, however, demodulated by a low-IF architecture. All the filtering, demodulation, gain control, synchronization and packet handling is performed digitally, which allows a very wide range of bit rates and frequency deviations to be selected. The receiver is also capable of automatic gain calibration in order to improve precision on RSSI measurements.

3.4.1. Block Diagram

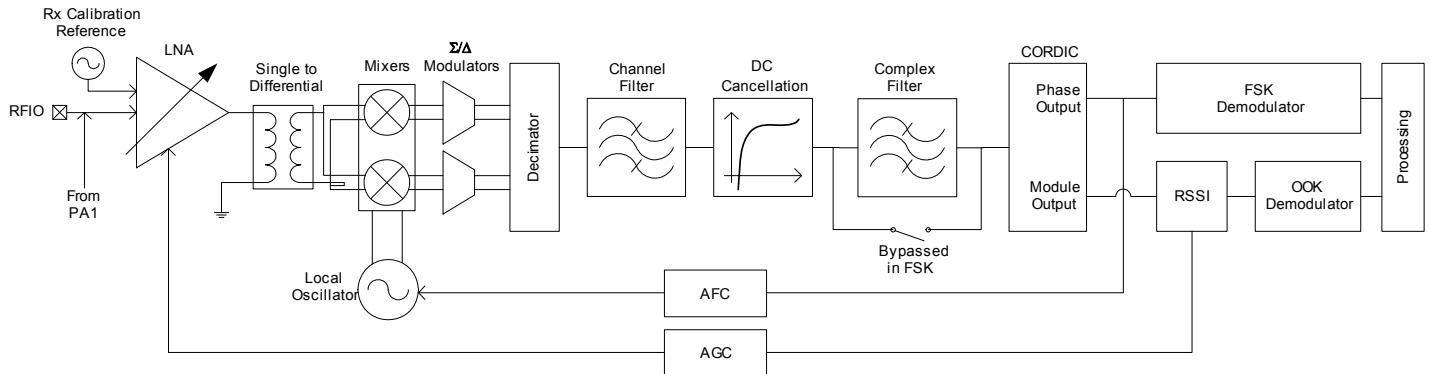


Figure 7. Receiver Block Diagram

The following sections give a brief description of each of the receiver blocks.

3.4.2. LNA - Single to Differential Buffer

The LNA uses a common-gate topology, which allows for a flat characteristic over the whole frequency range. It is designed to have an input impedance of 50 Ohms or 200 Ohms (as selected with bit *LnaZin* in *RegLna*), and the parasitic capacitance at the LNA input port is cancelled with the external RF choke. A single to differential buffer is implemented to improve the second order linearity of the receiver.

The LNA gain, including the single-to-differential buffer, is programmable over a 48 dB dynamic range, and control is either manual or automatic with the embedded AGC function.

Note In the specific case where the LNA gain is manually set by the user, the receiver will not be able to properly handle FSK signals with a modulation index smaller than 2 at an input power greater than the 1dB compression point, tabulated in section 3.4.3.

Table 12 LNA Gain Settings

<i>LnaGainSelect</i>	LNA Gain	Gain Setting
000	Any of the below, set by the AGC loop	-
001	Max gain	G1
010	Max gain - 6 dB	G2
011	Max gain - 12 dB	G3
100	Max gain - 24 dB	G4
101	Max gain - 36 dB	G5
110	Max gain - 48 dB	G6
111	Reserved	-

3.4.3. Automatic Gain Control

By default ($LnaGainSelect = 000$), the LNA gain is controlled by a digital AGC loop in order to obtain the optimal sensitivity/linearity trade-off.

Regardless of the data transfer mode (Packet or Continuous), the following series of events takes place when the receiver is enabled:

- ◆ The receiver stays in WAIT mode, until $RssiValue$ exceeds $RssiThreshold$ for two consecutive samples. Its power consumption is the receiver power consumption.
- ◆ When this condition is satisfied, the receiver automatically selects the most suitable LNA gain, optimizing the sensitivity/linearity trade-off.
- ◆ The programmed LNA gain, read-accessible with $LnaCurrentGain$ in $RegLna$, is carried on for the whole duration of the packet, until one of the following conditions is fulfilled:
 - ◆ Packet mode: if $AutoRxRestartOn = 0$, the LNA gain will remain the same for the reception of the following packet. If $AutoRxRestartOn = 1$, after the controller has emptied the FIFO the receiver will re-enter the WAIT mode described above, after a delay of $InterPacketRxDelay$, allowing for the distant transmitter to ramp down, hence avoiding a false RSSI detection. In both cases ($AutoRxRestartOn=0$ or $AutoRxRestartOn=1$), the receiver can also re-enter the WAIT mode by setting $RestartRx$ bit to 1. The user can decide to do so, to manually launch a new AGC procedure.
 - ◆ Continuous mode: upon reception of valid data, the user can decide to either leave the receiver enabled with the same LNA gain, or to restart the procedure, by setting $RestartRx$ bit to 1, resuming the WAIT mode of the receiver, described above.

Notes - the AGC procedure must be performed while receiving preamble in FSK mode
 - in OOK mode, the AGC will give better results if performed while receiving a constant "1" sequence

The following figure illustrates the AGC behavior:

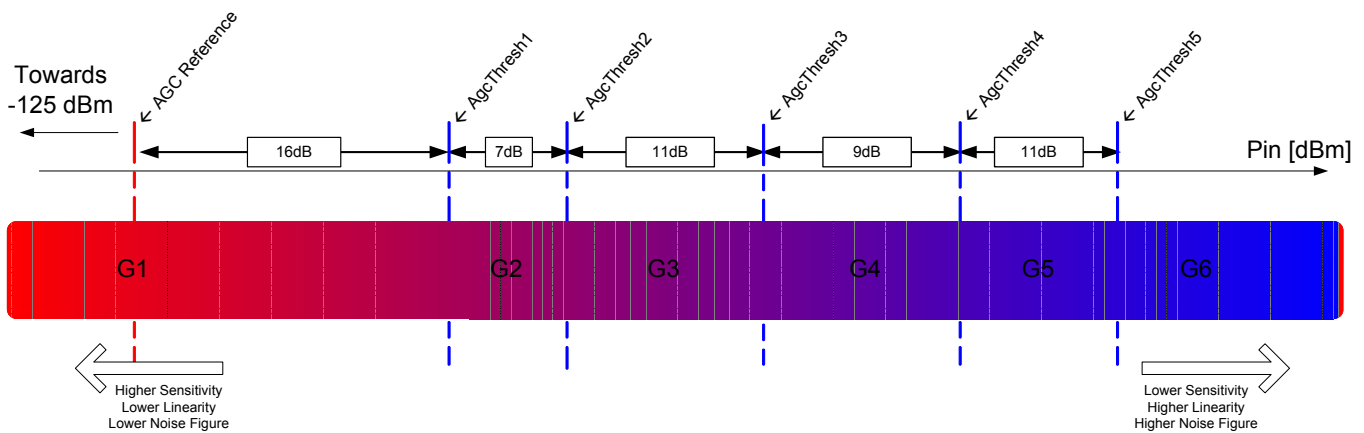


Figure 8. AGC Thresholds Settings

The following table summarizes the performance (typical figures) of the complete receiver:

Table 13 Receiver Performance Summary

Input Power <i>Pin</i>	Gain Setting	Receiver Performance (typ)			
		<i>P</i> _{-1dB} [dBm]	NF [dB]	IIP3 [dBm]	IIP2 [dBm]
<i>Pin</i> < AgcThresh1	G1	-37	7	-18	+35
AgcThresh1 < <i>Pin</i> < AgcThresh2	G2	-31	13	-15	+40
AgcThresh2 < <i>Pin</i> < AgcThresh3	G3	-26	18	-8	+48
AgcThresh3 < <i>Pin</i> < AgcThresh4	G4	-14	27	-1	+62
AgcThresh4 < <i>Pin</i> < AgcThresh5	G5	>-6	36	+13	+68
AgcThresh5 < <i>Pin</i>	G6	>0	44	+20	+75

3.4.3.1. *RssiThreshold* Setting

For correct operation of the AGC, *RssiThreshold* in *RegRssiThresh* must be set to the sensitivity of the receiver. The receiver will remain in WAIT mode until *RssiThreshold* is exceeded.

Note When AFC is enabled and performed automatically at the receiver startup, the channel filter used by the receiver during the AFC and the AGC is *RxBwAfc* instead of the standard *RxBw* setting. This may impact the sensitivity of the receiver, and the setting of *RssiThreshold* accordingly

3.4.3.2. AGC Reference

The AGC reference level is automatically computed in the SX1231H, according to:

$$\text{AGC Reference [dBm]} = -174 + \text{NF} + \text{DemodSnr} + 10 \cdot \log(2 \cdot \text{RxBw}) + \text{FadingMargin} \quad [\text{dBm}]$$

With:

- ◆ *NF* = 7dB : LNA's Noise Figure at maximum gain
- ◆ *DemodSnr* = 8 dB : SNR needed by the demodulator
- ◆ *RxBw* : Single sideband channel filter bandwidth
- ◆ *FadingMargin* = 5 dB : Fading margin

3.4.4. Continuous-Time DAGC

In addition to the automatic gain control described in section 3.4.3, the SX1231H is capable of continuously adjusting its gain in the digital domain, after the analog to digital conversion has occurred. This feature, named DAGC, is fully transparent to the end user. The digital gain adjustment is repeated every 2 bits, and has the following benefits:

- ◆ Fully transparent to the end user
- ◆ Improves the fading margin of the receiver during the reception of a packet, even if the gain of the LNA is frozen
- ◆ Improves the receiver robustness in fast fading signal conditions, by quickly adjusting the receiver gain (every 2 bits)
- ◆ Works in Continuous, Packet, and unlimited length Packet modes

The DAGC is enabled by setting *RegTestDagc* to 0x20 for low modulation index systems (i.e. when *AfcLowBetaOn*=1, refer to section 3.4.16), and 0x30 for other systems. It is recommended to always enable the DAGC.